

In series

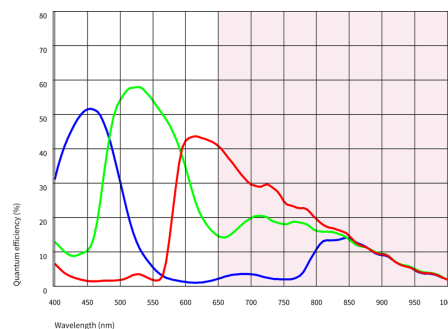
The model is in series and available for the long term.



Specification

Sensor

Sensor type	CMOS Color
Shutter	Global Shutter
Sensor characteristic	Linear
Readout mode	-
Pixel Class	8 MP
Resolution	8.13 Mpix
Resolution (h x v)	2856 x 2848 Pixel
Aspect ratio	1:1
ADC	12 bit
Color depth (camera)	12 bit
Optical sensor class	2/3"
Optical Size	7.825 mm x 7.804 mm
Optical sensor diagonal	11.07 mm (1/1.45")
Pixel size	2.74 µm
Manufacturer	Sony
Sensor Model	IMX546-AAQJ-C
Gain (master/RGB)	16x/16x
AOI horizontal	same frame rate
AOI vertical	increased frame rate
AOI image width / step width	256 / 2
AOI image height / step width	2 / 2
AOI position grid (horizontal/vertical)	2 / 2
Binning horizontal	
Binning vertical	
Binning method	M/C automatic
Binning factor	2 / 4 / 8
Subsampling horizontal	increased frame rate
Subsampling vertical	increased frame rate
Subsampling method	M/C automatic
Subsampling factor	2, 4, 8



Model

Frame rate freerun mode	15 fps
Frame rate trigger (continuous)	15 fps
Frame rate trigger (maximum)	16 fps
Exposure time (minimum - maximum)	0.064 ms - 2000 ms
Long exposure (maximum)	120000 ms
Power consumption	1.6 W - 4.2 W
Image memory	128 MB

Ambient conditions

For PCB versions, refer to the separate hints in the respective documentation.

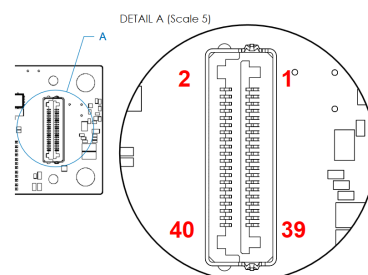
Allowed device temperature during operation	0 °C - 55 °C / 32 °F - 131 °F
Allowed device temperature during storage	-20 °C - 60 °C / -4 °F - 140 °F
Humidity (relative, non-condensing)	20 % - 80 %

Connectors

Interface connector	Samtec LSHM 40pol
I/O connector	40-pin header (Samtec LSHM-120-L2.5-L-DV-A-S-K-TR)
Power supply	12 V - 24 V

Pin assignment I/O connector

1	Input power supply (VCC) 12-24 V DC $\pm$ 10 %
2	Do not connect (for future use)
3	Input power supply (VCC) 12-24 V DC $\pm$ 10 %
4	Do not connect (for future use)
5	Ground (GND)
6	Do not connect (for future use)
7	Flash output without optocoupler 3.15 V 8 mA
8	Do not connect (for future use)
9	Trigger input without optocoupler 3.15 V
10	Ground (GND)
11	Do not connect (for future use)
12	Ground (GND)
13	Do not connect (for future use)
14	Do not connect (for future use)
15	I2C SDA (signal data) 3.15 V
16	Do not connect (for future use)
17	I2C SCL (signal clock) 3.15 V
18	Do not connect (for future use)
19	Do not connect (for future use)
20	RJ45 MX0 (-)
21	Do not connect (for future use)
22	RJ45 MX0 (+)
23	General Purpose I/O (GPIO) 2, 3.15 V 8 mA
24	Do not connect (for future use)
25	General Purpose I/O (GPIO) 1, 3.15 V 8 mA
26	RJ45 MX1 (-)
27	Ethernet, LED green, output 3.15 V
28	RJ45 MX1 (+)
29	Power, LED green, output 3.15 V
30	Do not connect (for future use)
31	Power, LED red, output 3.15 V
32	RJ45 MX2 (+)
33	Ethernet, LED red, output 3.15 V
34	RJ45 MX2 (-)
35	Do not connect (for future use)
36	Do not connect (for future use)
37	Do not connect (for future use)
38	RJ45 MX3 (+)
39	Ground (GND)
40	RJ45 MX3 (-)



Design

Lens Mount	C-Mount
IP code	-
Dimensions H/W/L	84.0 mm x 40.0 mm x 29.7 mm
Mass	34 g
Housing material	-

Features

List of on-camera image pre-processing features.

All features of the table are available via our IDS peak software for image pre-processing on the host computer (sensor model dependent).

Image Acquisition	Freerun	✓
	Software trigger	✓
	Hardware trigger	✓
	Trigger controlled exposure	✓
	Denoiser	✓
	Long exposure	✓
	Line scan	✓
Flashing	Flashing	✓
	PWM flashing	✓
Image Adjustments	Auto exposure	✓
	Auto gain	✓
	Auto whitebalance	✓
	Color correction	✓
	Gamma	✓
	LUT	✓
	Mirror/flip	X/Y
On-board Image Processing	Pixel formats	Mono8 BayerRG8 BayerRG10 BayerRG10p BayerRG12 BayerRG12p BGR8 RGB8 BGR10p32 RGB10p32
	Region of interest	✓
	Decimation (FPGA)	✓
	Decimation (Sensor)	2x2
	Binning (FPGA)	✓
	Binning (Sensor)	
Others	IP settings	✓
	Bandwidth management	✓
	Chunks	✓
	Sequencer	✓
	PTP	✓
	Firmware update	✓
	1st supported firmware version	3.31